

Travelling Merchant: \_\_\_\_\_

# DATASHEET

Standard: DP7W25000007

Plot			The Label
Drew	Audited	Approved	Stamp, please! Thanks!
Date: 2017.12.22			

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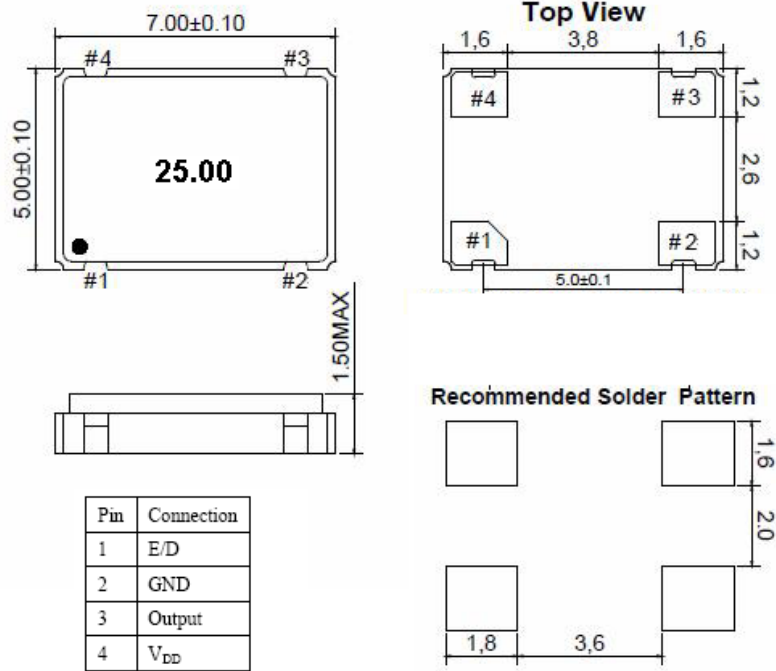


## 1. Electrical Parameters

MODEL: DP7W25000007							
No.	Parameters	SYM.	Electrical Spec.				Notes
			Min.	Typ.	Max.	Units	
1	Nominal Frequency	FL	25.00			MHz	
2	Supply Voltage	VDD	2.97	3.3	3.63	V	
3	Current consumption	-	-	-	10	mA	
4	Output Waveform	-	HCMOS			-	
5	Standard Output Load	-	15pF				
6	Frequency Stability	-	-25	~	+25	$\times 10^{-6}$	condition*: Include 25deg C tolerance, operating temperature range , input voltage change, aging, load change, shock and vibration.
7	Operating Temperature	Topr	-40	-	+85	°C	
8	Storage Temperature	Tstg	-55	-	+125	°C	
9	Duty Cycle	-	40	50	60	%	
10	Start-up Time	Tosc	-	-	10	mS	
11	Rise/Fall Time	Tr/Tf	-	-	6	nS	
12	Output High Logic1	-	90%			VDD	
13	Output Low Logic0	-			10%	VDD	
14	Aging	-	-2	-	+2	$\times 10^{-6}$	Frequency drift in first year
15	Pin 2, E/D function	pin 2=H or open.....output active at pin 4 pin 2=L.....high impedance at pin 4					



## 2、Mechanical Structure(mm)



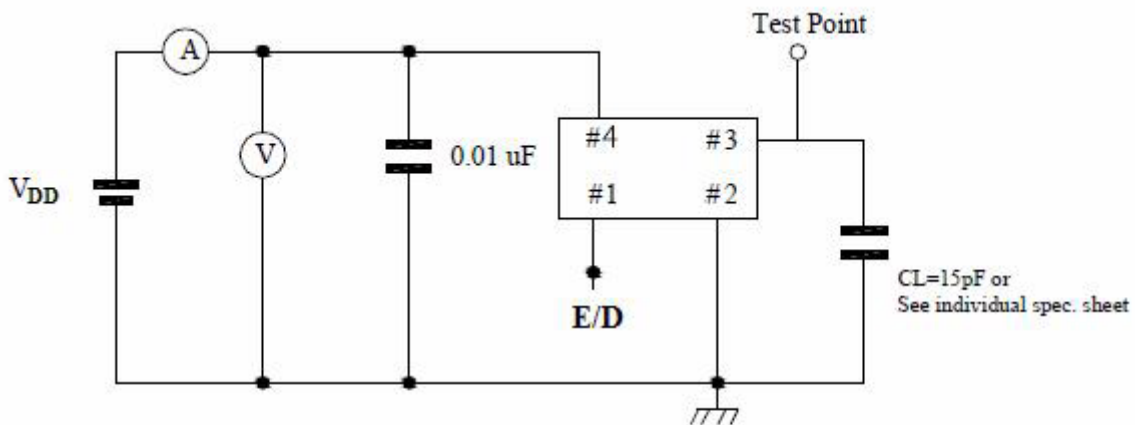
**Note1:** Tolerance  $\pm 0.2\text{mm}$

**Note2:** 0.01uF bypass capacitor should be placed between VDD (pin 6) and GND (pin 3) to minimize power supply line noise.

**Note3:** Line shouldn't be layed under the oscillator in the PCB to minimize signal interference.

**Note4:** The Load we advise is only 15pF (that means drive only 1 CMOS/TTL gate).

## 3、Test Circuit



Enable/Disable Function	
Input (pin 1)	Output (pin 3)
Open	Enable
$V_{IH} \geq 0.7V_{DD}$	Enable
$V_{IL} \leq 0.3V_{DD}$	Disable

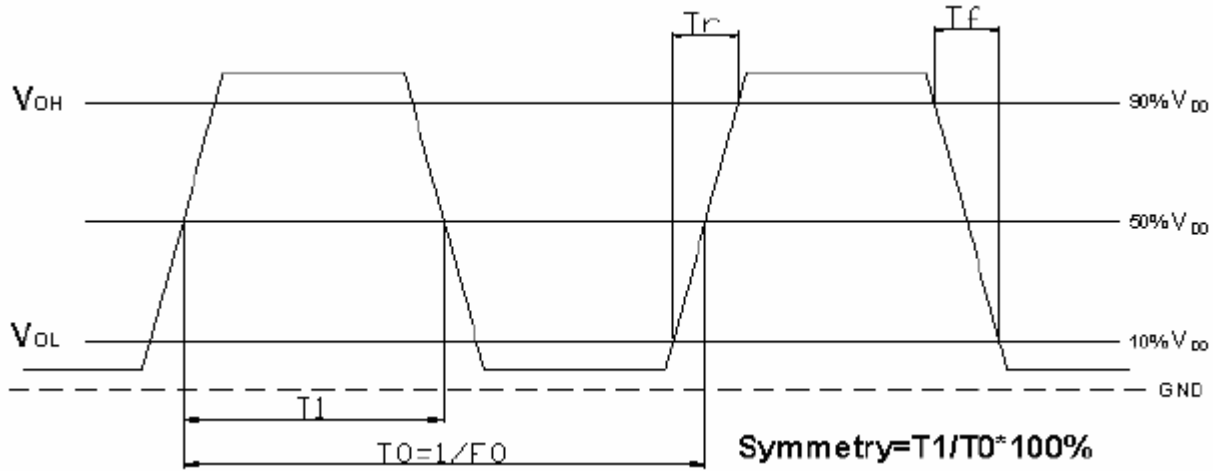


#### 4、 Reliability Specifications

No.	Test Item	Test Conditions	Reference
1	High Temperature Storage	Temperature: 125℃ ±5℃ Time: 1000±24 Hours	MIL-STD-883E-1016
2	Temperature Cycle	Temperature 1: -55℃ ±5℃ Temperature 2: 125℃ ±5℃ Temperature change between T1 and T2 at soonest Run 10 cycles, maintain T1 and T2 15minutes each in one cycle	MIL-STD-883E-1011.9B
3	Solder Heat Resistance	Pre-heat: 125℃ 60~120 Seconds Solder Temperature: 260℃ ±5℃ Time: 30 Seconds	MIL-STD-202F 210 E
4	Drop Test	3 Times Free Fall from 75cm height table to 3cm thickness hard wood board	MIL-STD-202F-203B
5	High Temperature, High Humidity Storage	Temperature: 85℃ ±5℃ Relative Humidity: 80%~85% Time: 250Hours±24 Hours	MIL-STD-202 F-103B
6	Steam Aging	Temperature: 97℃ ±5℃ Time: 8 Hours 260℃ solder pot to check solderability	MIL-STD-883 C-1008.2B
7	Solderability	Dip in flux 5~10 seconds Temperature: 245℃ ±5℃ Time: 10 Seconds	MIL-STD-883E 2003
8	Aging	Temperature: 85℃ ±5℃ Time: 250±12Hours	MIL-STD-202 F-108A B
9	Thermal Shock	Temperature 1: -55℃ ±5℃ Temperature 2: 125℃ ±5℃ Temperature change between T1 and T2: 5 seconds 10 cycles, maintain T1 and T2 for 30 minutes each in one cycle	MIL-STD-883E-1011.9B
10	Vibration	Frequency Range: 10Hz~2000Hz Amplitude: 1.5mm or 20G 4Hours in each direction, total 12Hours	MIL-STD-202F

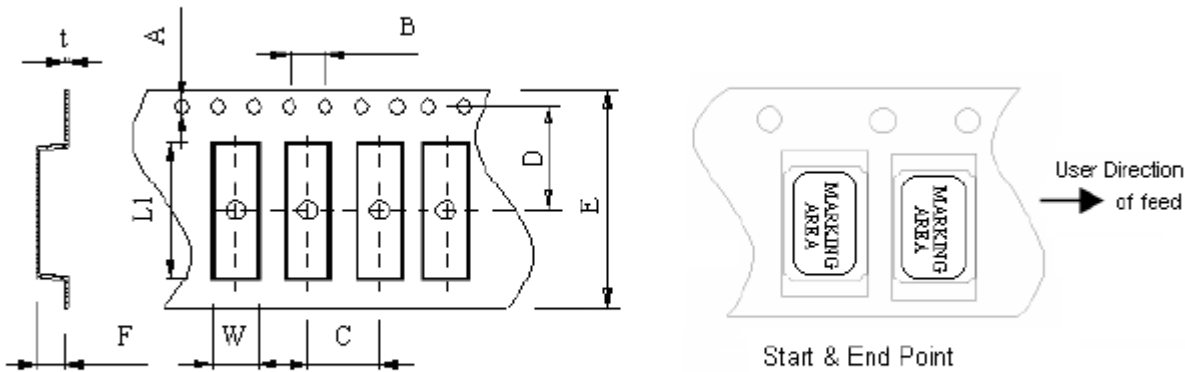


### 5、 Output Waveform



### 6、 Package: Tape & Reel (mm)

Tape Dimensions(unit : mm)



A	B	C	D	E	F	L1	W	t
1.50±0.1	4.0±0.1	8.0±0.1	7.5±0.1	16.0±0.2	2.0	7.4±0.1	5.4±0.1	0.3